

## 100V P-Channel Enhancement Mode MOSFET

**Description**

The PECN30P10G uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

**General Features**

- ◆  $V_{DS} = -100V$   $I_D = -30A$   
 $R_{DS(ON)}(\text{Typ.}) = 36m\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(ON)}(\text{Typ.}) = 40m\Omega$  @  $V_{GS} = -4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

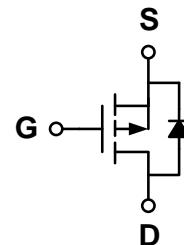
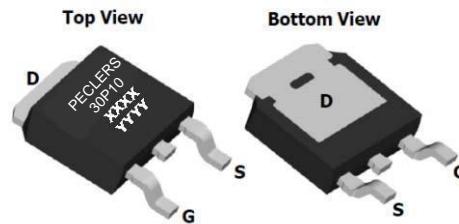
**Application**

- ◆ Load switch

**Package**

- ◆ TO-252-2L

*100% UIS TESTED!*  
*100%  $\Delta V_{ds}$  TESTED!*

**Schematic diagram****Marking and pin assignment**

30P10—PECN30P10  
XXXX—Wafer Lot No.  
YYYY—Quality Code

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN30P10G	-55°C to +150°C	TO-252-2L	2500

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	-100	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_J = 150^{\circ}\text{C}$ ) <sup>b</sup>	$T_C = 25^{\circ}\text{C}$	-36	A
	$T_C = 70^{\circ}\text{C}$	-29	
	$T_A = 25^{\circ}\text{C}$	-9 <sup>b,c</sup>	
	$T_A = 70^{\circ}\text{C}$	-7.2 <sup>b,c</sup>	
Pulsed Drain Current	$I_{DM}$	-40	
Continuous Source Current (Diode Conduction)	$T_C = 25^{\circ}\text{C}$	-50 <sup>a</sup>	
	$T_A = 25^{\circ}\text{C}$	-5.75 <sup>b,c</sup>	
Avalanche Current	$I_{AS}$	-35	
Single Pulse Avalanche Energy	$E_{AS}$	61	mJ

Maximum power dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	113	W
	T <sub>C</sub> =70°C		72	
	T <sub>A</sub> =25°C		6.9 <sup>b,c</sup>	
	T <sub>A</sub> =70°C		4.4 <sup>b,c</sup>	
Operating Junction and Storage Temperature Range		T <sub>J,T<sub>STG</sub></sub>	-55—150	°C

## Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Unit
Thermal Resistance-Junction to Case	R <sub>θJC</sub>	0.85	1.1	°C/W
Thermal Resistance junction-to ambient <sup>a</sup>	t≤10s	15	18	
	Steady State	40	50	

Notes:

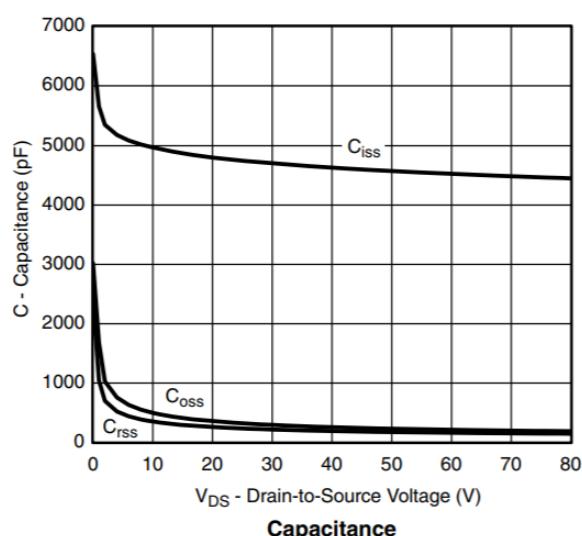
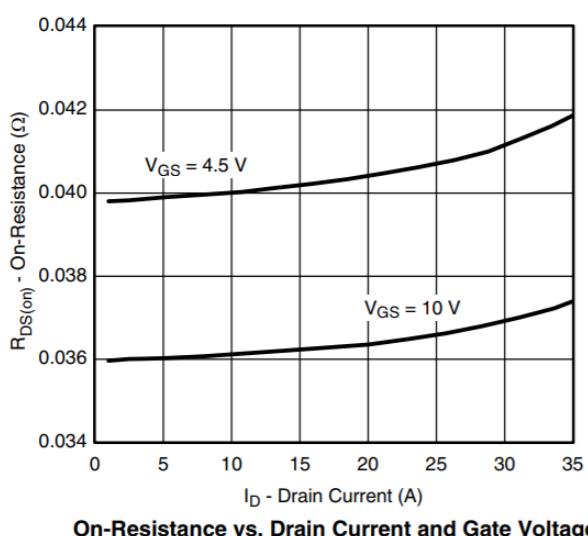
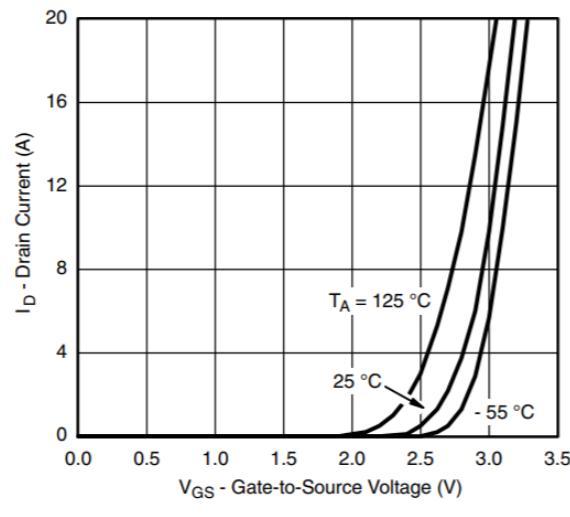
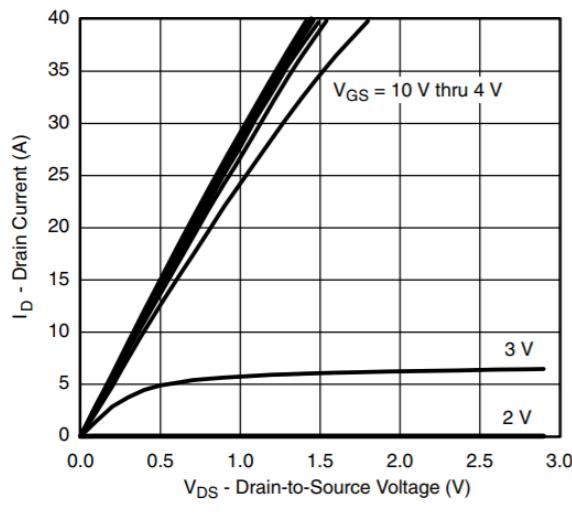
- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 50 °C/W.

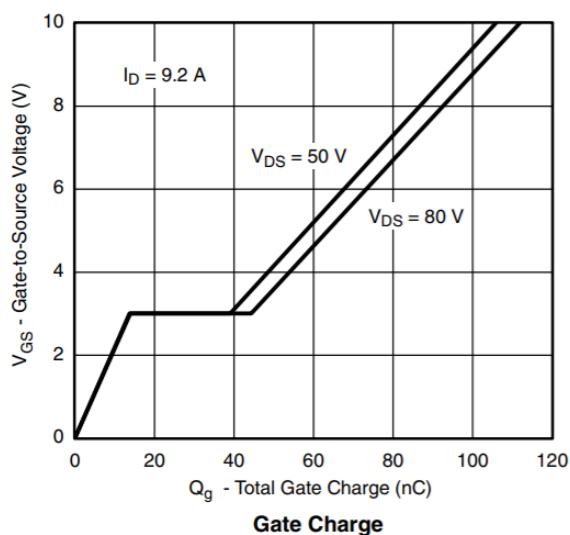
## Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-100	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	-	-	-25	μA
		V <sub>DS</sub> =-80V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	-	-	-100	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-1.9	-3.0	V
Drain-source on-state resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-30A	-	36	43	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	-	40	48	
Forward Transconductance	G <sub>FS</sub>	V <sub>DS</sub> =-15V, I <sub>D</sub> =-10A	-	38	-	S
<b>Diode Characteristics<sup>2</sup></b>						
Diode Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>SD</sub> =-7.7A, V <sub>GS</sub> =0V	-	-0.8	-1.2	V
Diode Continuous Forward Current	I <sub>s</sub>	T <sub>C</sub> = 25 °C	-	-	-50	A
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =-7A, dI/dt=-100A/us	-	60	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	150	-	nC
<b>Dynamic Characteristics<sup>2</sup></b>						
Gate Resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	-	4	-	Ω
Input capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-50V f=1.0MHz	-	4600	-	pF
Output capacitance	C <sub>OSS</sub>		-	230	-	
Reverse transfer capacitance	C <sub>RSS</sub>		-	175	-	
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>GS</sub> =-10V, V <sub>DD</sub> =-50V,	-	15	-	ns

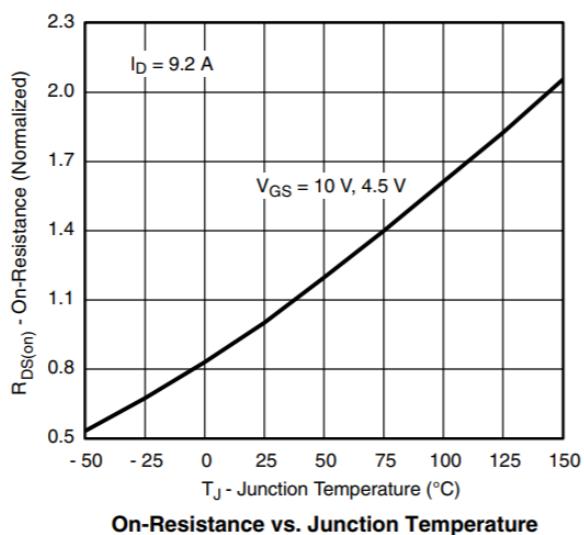
Turn-on Rise time	$t_r$	RD=2.4Ω, ID=-7.7A, RG=1Ω	-	20	-	nC
Turn-off delay time	$t_{D(OFF)}$		-	110	-	
Turn-off Fall time	$t_f$		-	100	-	
Total gate charge	$Q_g$	$V_{GS}=-4.5V, I_D=-9A$ $V_{DS}=-50V$	-	54		nC
Gate-source charge	$Q_{gs}$			14		
Gate-drain charge	$Q_{gd}$		-	26	-	

### Typical Performance Characteristics

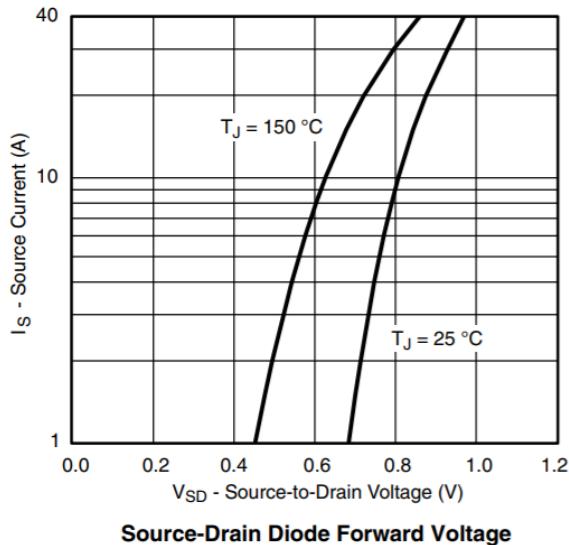




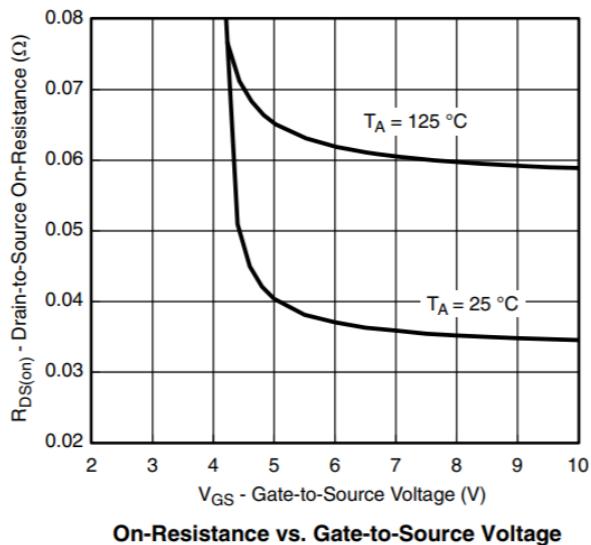
**Gate Charge**



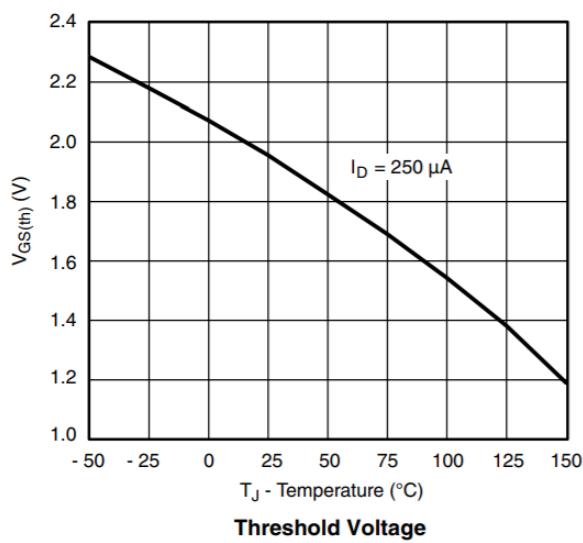
**On-Resistance vs. Junction Temperature**



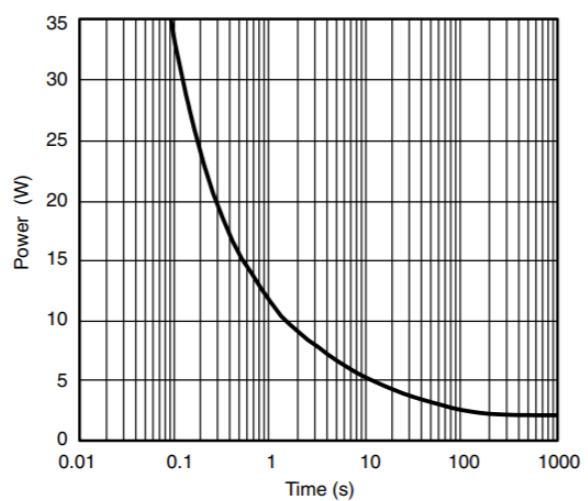
**Source-Drain Diode Forward Voltage**



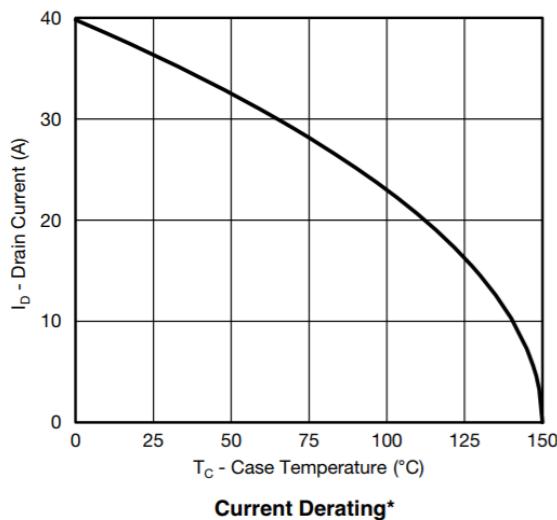
**On-Resistance vs. Gate-to-Source Voltage**



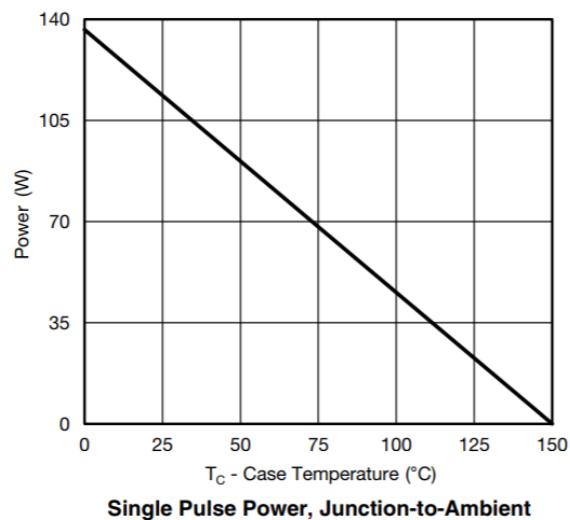
**Threshold Voltage**



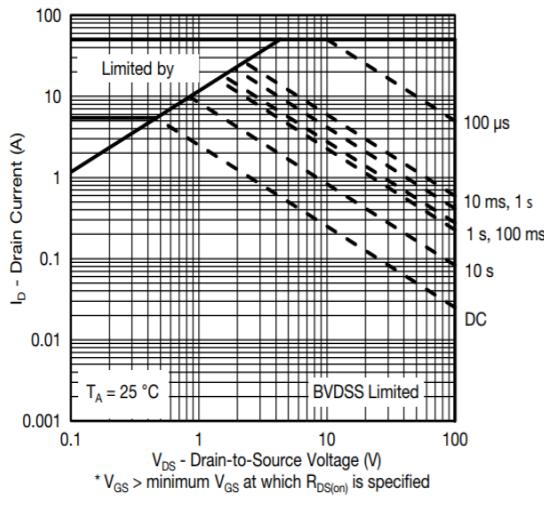
**Single Pulse Power, Junction-to-Ambient**



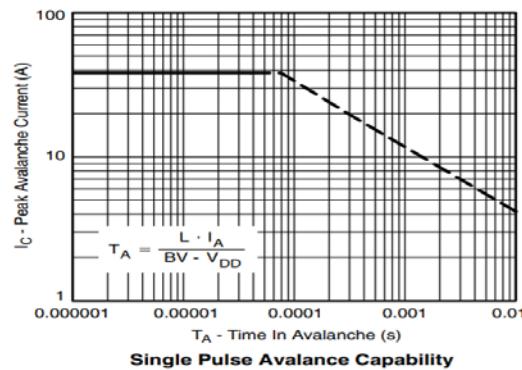
**Current Derating\***



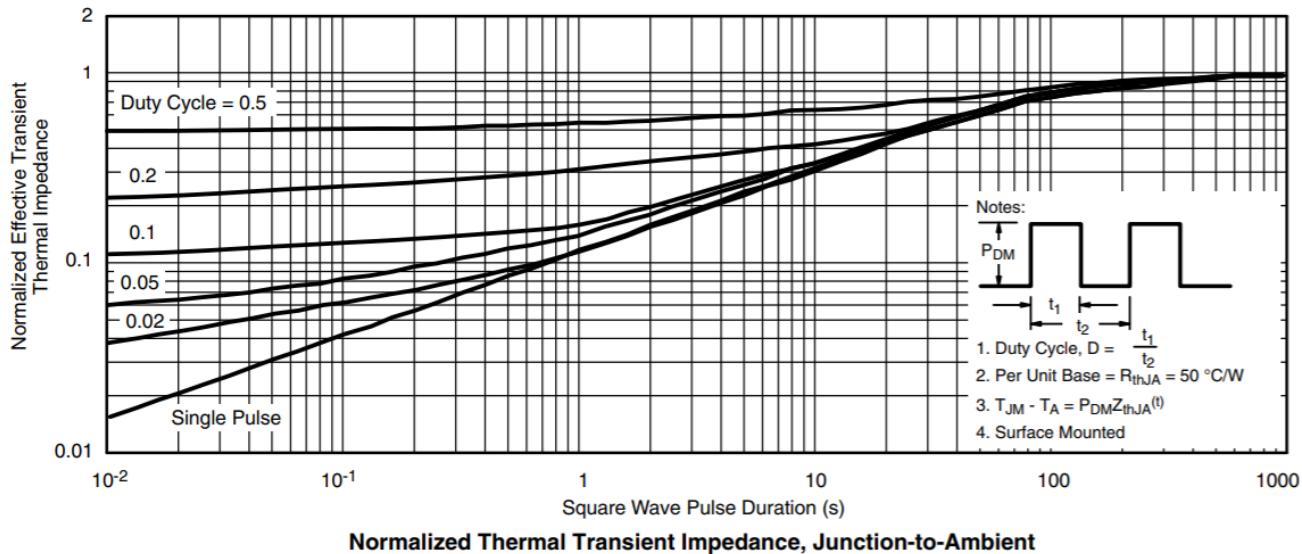
**Single Pulse Power, Junction-to-Ambient**



**Safe Operating Area, Junction-to-Ambient**



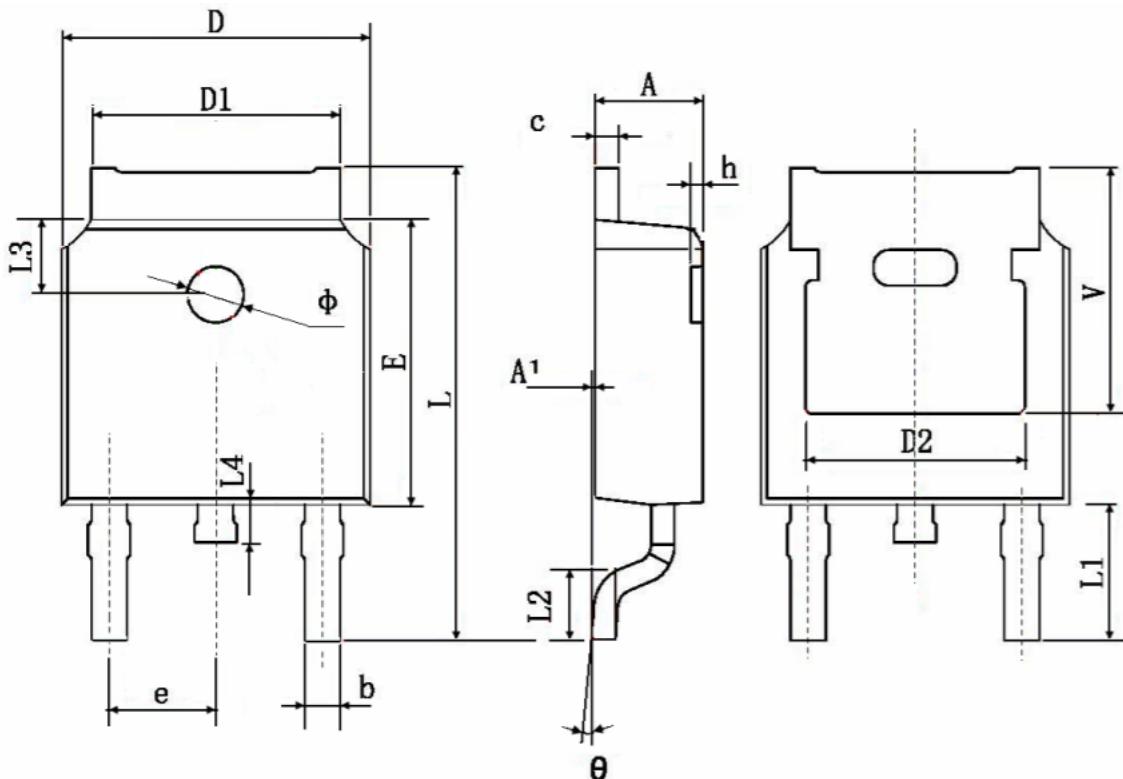
**Single Pulse Avalanche Capability**



**Normalized Thermal Transient Impedance, Junction-to-Ambient**

## Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	